BLP05H9S500P

Power LDMOS transistor Rev. 1 — 10 September 2019

AMPLEON

Product data sheet

Product profile 1.

1.1 General description

500 W LDMOS power transistor for various applications such as ISM, RF plasma lighting and defrosting at frequencies from 423 MHz to 443 MHz.

Typical performance

RF performance at V_{DS} = 50 V; I_{Dq} = 50 mA in a class-AB application circuit.

Test signal	f	V _{DS}	P _L	Gp	ησ
	(MHz)	(V)	(W)	(dB)	(%)
CW	433	50	500	25.3	75
CW pulsed [1]	433	50	500	25.6	75.8

^[1] $t_p = 100 \mu s$; $\delta = 10 \%$.

1.2 Features and benefits

- High efficiency
- Easy power control
- Excellent ruggedness
- Integrated ESD protection
- Designed for ISM operation (423 MHz to 443 MHz)
- Excellent thermal stability
- For RoHS compliance see the product details on the Ampleon website

1.3 Applications

■ RF power amplifiers for CW and pulsed CW applications in the 423 MHz to 443 MHz frequency range such as ISM, RF plasma lighting and defrosting

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	gate 2		4
2	gate 1	4 3	4
3	drain 1		
4	drain 2		2 5
			3 aaa-003574

3. Ordering information

Table 3. Ordering information

Type number	Packag	ge			
	Name	Description	Version		
BLP05H9S500P	-	plastic, heatsink small outline package; 4 leads (flat)	OMP-780-4F-1		

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Min	Max	Unit
V_{DS}	drain-source voltage	-	108	V
V_{GS}	gate-source voltage	-6	+11	V
T _{stg}	storage temperature	- 65	+150	°C
Tj	junction temperature [1]	-	225	°C

^[1] Continuous use at maximum temperature will affect the reliability, for details refer to the online MTF calculator.

5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Тур	Unit
R _{th(j-c)}	thermal resistance from junction to case	T _{case} = 90 °C; P _L = 500 W	0.22	K/W

6. Characteristics

Table 6. DC characteristics

 T_i = 25 °C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$V_{(BR)DSS}$	drain-source breakdown voltage	$V_{GS} = 0 \text{ V}; I_D = 1.8 \text{ mA}$	108	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	V _{DS} = 10 V; I _D = 180 mA	1.5	2.1	2.5	V
I _{DSS}	drain leakage current	V _{GS} = 0 V; V _{DS} = 50 V	-	-	2.8	μА
I _{DSX}	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75 \text{ V};$ $V_{DS} = 10 \text{ V}$	-	31	-	Α
I _{GSS}	gate leakage current	V _{GS} = 11 V; V _{DS} = 0 V	-	-	280	nA
g _{fs}	forward transconductance	$V_{DS} = 10 \text{ V}; I_{D} = 9 \text{ A}$	-	13	-	S
R _{DS(on)}	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75 \text{ V};$ $I_D = 6.3 \text{ A}$	-	0.12	-	Ω

Table 7. RF characteristics

Test signal: CW pulsed (t_p = 100 μ s; δ = 10 %); f = 443 MHz; RF performance at V_{DS} = 50 V; I_{Dq} = 100 mA; T_{case} = 25 °C; unless otherwise specified; in a class-AB production test circuit.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
G _p	power gain	P _L = 500 W	24	25.2	-	dB
RLin	input return loss	P _L = 500 W	-	-14.5	-9	dB
η_{D}	drain efficiency	P _L = 500 W	68	72	-	%

7. Test information

7.1 Ruggedness in class-AB operation

The BLP05H9S500P is capable of withstanding a load mismatch corresponding to VSWR = 10 : 1 through all phases under the following conditions: V_{DS} = 50 V; I_{Dg} = 50 mA; P_{L} = 500 W (CW).

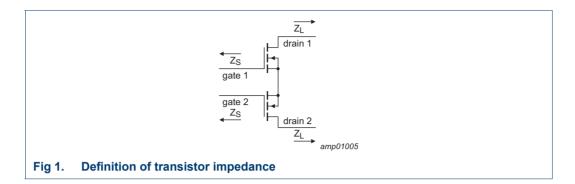
7.2 Impedance information

Table 8. Typical impedance

Measured load-pull Z_S and Z_L device impedances per section; I_{Dq} = 25 mA per section; V_{DS} = 50 V; typical values unless otherwise specified.

f	Z _S [1]	Z _L [1]
(MHz)	(Ω)	(Ω)
433	1.3 – 2.1j	2.8 + 2.4j

[1] Z_S and Z_L defined in Figure 1.



7.3 Application circuit

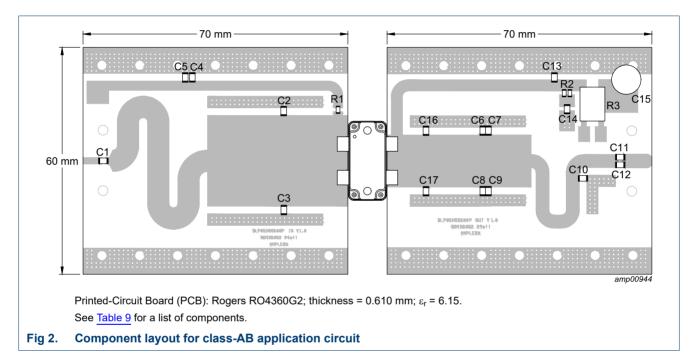


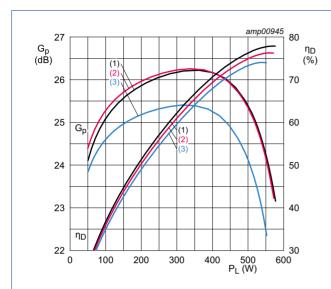
Table 9. List of components For test circuit see Figure 2.

Component	Description	Value	Remarks
C1, C4, C11, C12, C13	multilayer ceramic chip capacitor	270 pF	ATC800B
C2, C3	multilayer ceramic chip capacitor	75 pF	ATC800B
C5, C14	multilayer ceramic chip capacitor	4.7 μF, 100V	C3225X7S2A475K200AE
C6, C8	multilayer ceramic chip capacitor	27 pF	ATC800B
C7, C9	multilayer ceramic chip capacitor	18 pF	ATC800B
C10	multilayer ceramic chip capacitor	12 pF	ATC800B
C15	electrolytic capacitor	4.7 μF, 63 V	MAL203858471E3
C16, C17	multilayer ceramic chip capacitor	16 pF	ATC800B
R1	chip resistor	10 Ω	0806
R2, R4	chip resistor	9.1 Ω	1206
R3	shunt resistor	0.01 Ω	Ohmite: FC4L110R010FER

BLP05H9S500P

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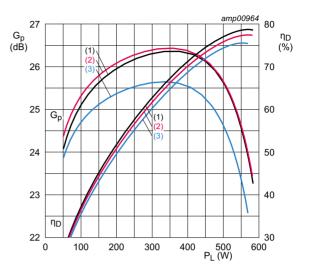
7.4 Graphical data



 V_{DS} = 50 V; I_{Dq} = 50 mA; CW.

- (1) f = 423 MHz
- (2) f = 433 MHz
- (3) f = 443 MHz

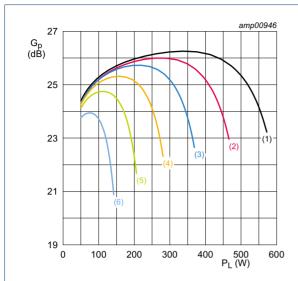
Fig 3. Power gain and drain efficiency as function of output power; typical values



 V_{DS} = 50 V; I_{Dq} = 50 mA; CW pulsed; t_p = 100 $\mu s;$ δ = 10 %.

- (1) f = 423 MHz
- (2) f = 433 MHz
- (3) f = 443 MHz

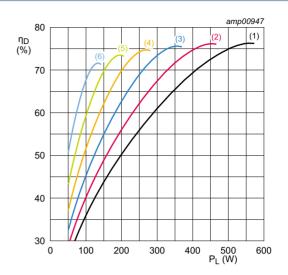
Fig 4. Power gain and drain efficiency as function of output power; typical values



f = 433 MHz; $I_{Dq} = 50 \text{ mA}$; CW.

- (1) $V_{DS} = 50 \text{ V}$
- (2) $V_{DS} = 45 \text{ V}$
- (3) $V_{DS} = 40 \text{ V}$
- (4) $V_{DS} = 35 \text{ V}$
- (5) $V_{DS} = 30 \text{ V}$
- (6) $V_{DS} = 25 \text{ V}$

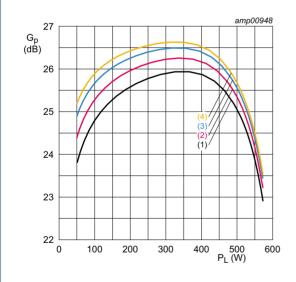
Fig 5. Power gain as a function of output power; typical values



 $f = 433 \text{ MHz}; I_{Dq} = 50 \text{ mA}; CW.$

- (1) $V_{DS} = 50 \text{ V}$
- (2) $V_{DS} = 45 \text{ V}$
- (3) $V_{DS} = 40 \text{ V}$
- (4) $V_{DS} = 35 V$
- (5) $V_{DS} = 30 \text{ V}$
- (6) $V_{DS} = 25 V$

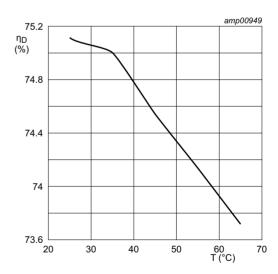
Fig 6. Drain efficiency as a function of output power; typical values



 V_{DS} = 50 V; f = 433 MHz; CW.

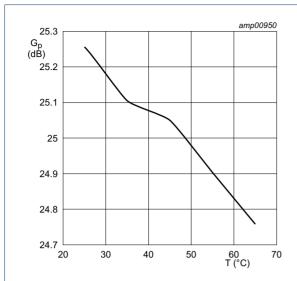
- (1) $I_{Dq} = 20 \text{ mA}$
- (2) $I_{Dq} = 50 \text{ mA}$
- (3) $I_{Dq} = 100 \text{ mA}$
- (4) $I_{Dq} = 150 \text{ mA}$

Fig 7. Power gain as a function of output power; typical values



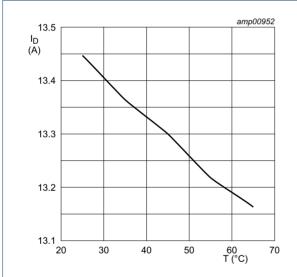
 V_{DS} = 50 V; I_{Dq} = 50 mA; f = 433 MHz; CW; at $P_{L(1dB)}$.

Fig 8. Drain efficiency as a function of temperature; typical values



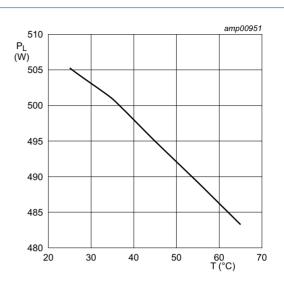
 V_{DS} = 50 V; I_{Dq} = 50 mA; f = 433 MHz; CW; at $P_{L(1dB)}$.

Fig 9. Power gain as a function of temperature; typical values



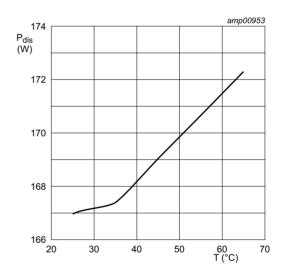
 V_{DS} = 50 V; I_{Dq} = 50 mA; f = 433 MHz; CW; at $P_{L(1dB)}$.

Fig 11. Drain current as a function of temperature; typical values



 V_{DS} = 50 V; I_{Dq} = 50 mA; f = 433 MHz; CW; at $P_{L(1dB)}$.

Fig 10. Output power as a function of temperature; typical values



 V_{DS} = 50 V; I_{Dq} = 50 mA; f = 433 MHz; CW; at $P_{L(1dB)}$.

Fig 12. Power dissipation as a function of temperature; typical values

8. Package outline

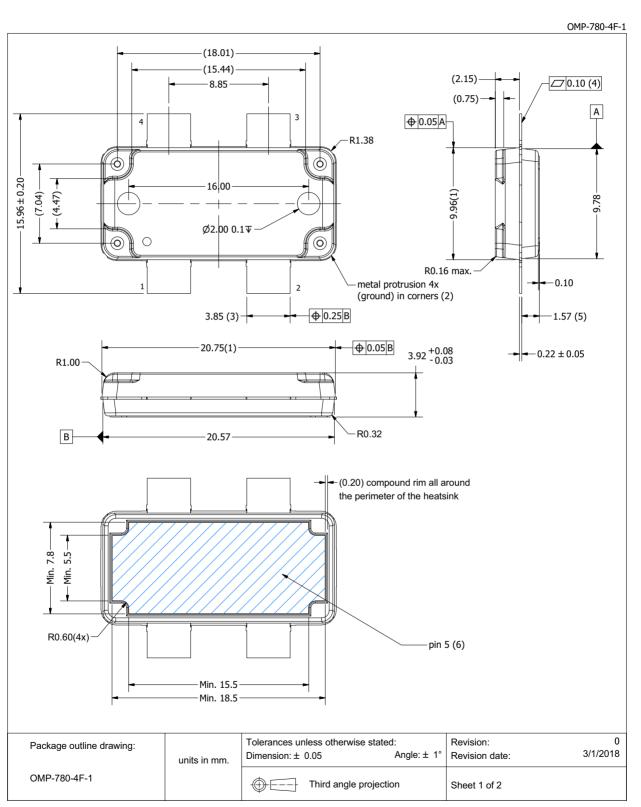


Fig 13. Package outline OMP-780-4F-1 (sheet 1 of 2)

OMP-780-4F-1

	Drawing Notes
Items	Description
	Dimensions are excluding mold protrusion. All areas located adjacent to the leads have a maximum mold protrusion of 0.25
(1)	mm (per side) and max. 0.62 mm in length.
	At all other areas the mold protrusion is maximum 0.15 mm per side. See also detail B.
(2)	The metal protrusion (tie bars) in the corner will not stick out of the molding compound protrusions (detail A).
(3)	The lead dambar (metal) protrusions are not included. Add 0.14 mm max to the total lead dimension at the dambar location.
(4)	The lead coplanarity over all leads is 0.1 mm maximum.
(5)	Dimension is measured 0.5 mm from the edge of the top package body.
(6)	The hatched area indicates the exposed metal heatsink.
(7)	The leads and exposed heatsink are plated with matte Tin (Sn).

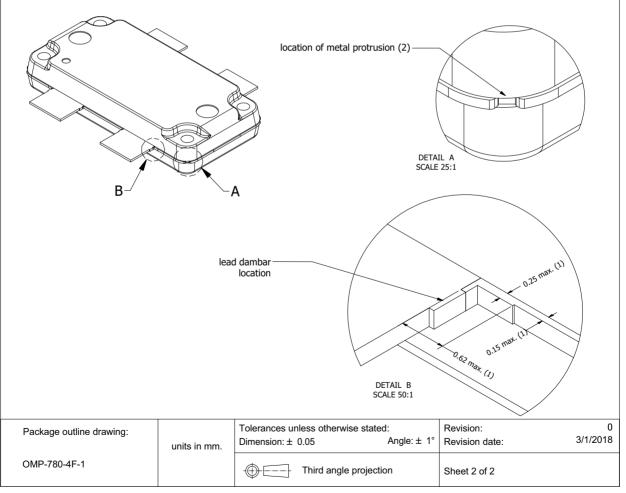


Fig 14. Package outline OMP-780-4F-1 (sheet 2 of 2)

9. Handling information

CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the ANSI/ESD S20.20, IEC/ST 61340-5, JESD625-A or equivalent standards.

Table 10. ESD sensitivity

ESD model	Class
Charged Device Model (CDM); According to ANSI/ESDA/JEDEC standard JS-002	C2A [1]
Human Body Model (HBM); According to ANSI/ESDA/JEDEC standard JS-001	2 [2]

- [1] CDM classification C2A is granted to any part that passes after exposure to an ESD pulse of 500 V.
- [2] HBM classification 2 is granted to any part that passes after exposure to an ESD pulse of 2000 V.

10. Abbreviations

Table 11. Abbreviations

Acronym	Description
CW	Continuous Wave
ESD	ElectroStatic Discharge
ISM	Industrial, Scientific and Medical
LDMOS	Laterally Diffused Metal-Oxide Semiconductor
MTF	Median Time to Failure
RoHS	Restriction of Hazardous Substances
VSWR	Voltage Standing Wave Ratio

11. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BLP05H9S500P v.1	20190910	Product data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions"
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Power LDMOS transistor

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13. Contact information

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For sales office addresses, please visit: http://www.ampleon.com/sales

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Power LDMOS transistor

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